

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

pplication of: William D. Sawyer, et al.

Serial No.:

10/642,315

Filed:

August 15, 2003

Title:

Method for Microfabricating Structures Using Silicon-On-Insulator Material

Docket:

CSLL-662CP (56247-235)

CERTIFICATE OF MAILING (37 C.F.R. § 1.8(a)

I hereby certify that this correspondence is being deposited with the United States Postal Service as First Class Mail under 37 CFR 1.8(a) in an envelope addressed to Mail Stop Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on the date indicated below.

Date:

W/18/04

Mail Stop Amendment Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

TRANSMITTAL LETTER

Applicant encloses herewith for filing in connection with the above-referenced patent application the following documents:

- 1) Information Disclosure Statement;
- 2) Information Disclosure Citation (PTO Form 1449);
- 3) Copies of the references cited; and
- Acknowledgment Postcard. 4)

No additional costs are believed to be due in connection with the filing of this disclosure. However, please charge any necessary fees to our Deposit Account No. 50-1133.

Respectfully submitted,

McDermott Will & Emery LLP

Customer No. 23630

Mark G. Lappin, Reg. No. 26,618

28 State Street

Boston, MA 02109-1775 Telephone: (617) 535-4043 Facsimile: (617) 535-3800



PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of: William D. Sawyer, et al.

Serial No.:

10/642,315

Filed:

August 15, 2003

Title:

Method for Microfabricating Structures Using Silicon-On-Insulator

Material

Docket:

CSLL-662CP (56247-235)

CERTIFICATE OF MAILING (37 C.F.R. § 1.8(a))

I hereby certify that this correspondence is being deposited with the United States Postal Service as First Class Mail under 37 CFR 1.8(a) in an envelope addressed to Mail Stop Amendment, Commissioner for Patents, PO Box 1450, Alexandria, VA 22313-1450 on the date indicated below.

Mail Stop Amendment Commissioner for Patents PO Box 1450 Alexandria, VA 22313-1450

Sir:

INFORMATION DISCLOSURE STATEMENT

In accordance with 37 C.F.R. §1.56, §1.97 and §1.98, Applicants hereby submit an information disclosure statement with information cited on the attached PTO-1449 form. According to the United States Patent and Trademark Office OG Notices: 05 August 2003, since the above-identified patent application was filed after June 30, 2003, copies of cited U.S. patents and U.S. patent application publications are waived and not submitted with this Statement.

This Statement is being filed before the receipt of any Official Action from the Patent and Trademark Office.

This statement is not to be interpreted as a representation that the cited publications are material, that an exhaustive search has been conducted, or that no other relevant information exists. Nor shall the citation of any publication herein be construed per se as a representation that such publication is prior art. Moreover, the Applicant understands that the Examiner will make an independent evaluation of the cited publications.

Serial No.: 10/642,315

Page - 2 -



No additional costs are believed to be due in connection with the filing of this disclosure. However, please charge any necessary fees to our Deposit Account No. 50-1133.

Respectfully submitted,

McDermott Will & Emery LLP

Customer No. 23630

Date: 10 18 14

Mark G. Lappin, Reg. No. 26,618

28 State Street

Boston, MA 02109-1775 Telephone: (617) 535-4043 Facsimile: (617) 535-3800

| | ON DIS | CLOSURE CIT | Docket Number (Optional) 56247-235 (CSLL-662CP) | | Application Number 10/642,315 | | | | |
|------------------------------------------------------------------------|--------|-------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|-------------------------------------------------------|-----------------|-----------------------------------------|-------|----------|----------------------------------------|-------------|
| IN AN APPLICATION OCT 2 0 2004 S Sawyer, et al. | | | | | | | | | |
| (Use several sheets if necessary) | | | | | Filing Date Group Art Unit 8/15/2003 | | | ······································ | |
| U. S. Patent Decuments | | | | | | | | | |
| EXAMINER INTIIAL | REF | DOCUMENT NUMBER | DATE | NAME | | CLASS | SUBCLASS | FILING IF APPRO | |
| | | 6,077,721 | 06-2000 | Fukuda et al. | | | | | |
| | | 6,277,666 | 08-2001 | Hays et al. | | | | | |
| | | 6,431,714 | 08-2002 | Sawada et al. | | | | | |
| | | 6,423,563 | 07-2002 | Fukads | | | | | |
| | | 4,079,508 | 03-1979 | Nunn | | | | | |
| | | 6,252,294 | 06-2002 | Hattori | | **** | | | |
| | | 6,171,881 | 01-2002 | Fujii | | | | | |
| | | 5,488,012 | 01-1996 | McCarthy | | | | | |
| | | 5,760,443 | 06-1998 | McCarthy | | | - | | |
| | | 3,922,705 | 11-1975 | Yerman | | | | | |
| | | 6,105,427 | 08-2000 | Stewart, et al. | | | | | |
| | | 6,458,615 | 10-2002 | Fedder, et al. | | | | | |
| | | 5,501,893 | 03-1996 | Laermer, et al. | | | | | |
| | | | | | | | | | |
| FOREIGN PATENT DOCUMENTS | | | | | | | | | |
| | REF | DOCUMENT NUMBER | DATE | | COUNTRY | CLASS | SUBCLASS | Transl YES | ation NO |
| | | | | | | | , | | |
| | | | | | | | | | |
| OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.) | | | | | | | | | |
| Copy of International Search Report PCT/US02/00015 | | | | | | | | | |
| | C1 | Moore DF, "Silicon-on insulator material for sensors and accelerometers" Silicon Fabricated Inertial instruments, 9/1-9/5 (December 1996) | | | | | | | |
| | C2 | Syms RRA et al., "Surface tension powered self-assembly of 3D MOEMS devices using DRIE of bonded silicon-on-insulator wafers." IEEE Seminar on Demonstrated Micromachining Technologies for Industry, 1/1-1/6 (March 2000) | | | | | | | |
| | C3 | Yamamoto T et al. "Capacitive accelerometer with high aspect ratio single crystalline silicon microstructure using SOI structure with polysilicon-based interconnect technique." Micro Electro Mechanical Systems, 515-519 (January 2000) | | | | | | | |
| | C4 | Martin A. Schmidt, "Wafer-to-Wafer Bonding for Microstructure Formation", Proceedings of the IEEE, Vol. 86, No. 8, August 1998. | | | | | | | |
| EXAMINER | | | | | DATE CONSIDERED | | | | |
| | | | | | s in conformance v th next communica | | | line thro | ıgh |

Subst. PTO-1449 (1-94)